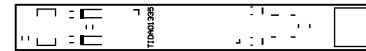


Z22

This Assembly Note will show in the PcbDoc and associated outputs
Z23

This Assembly Note will show in the PcbDoc and associated outputs
Z24

This Assembly Note will show in the PcbDoc and associated outputs



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01335		
PLOT NAME = Top Overlay	GENERATED : 7/18/2017 11:39:05 AM	TEXAS INSTRUMENTS	



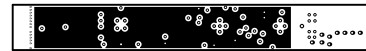
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01335		
PLOT NAME = Top Solder Mask	GENERATED : 7/18/2017 11:39:07 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01335		
PLOT NAME = Top Layer	GENERATED : 7/18/2017 11:39:08 AM		TEXAS INSTRUMENTS



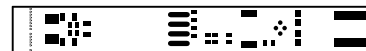
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 1	TID #: TIDA-01335		
PLOT NAME = Signal Layer 1	GENERATED : 7/18/2017 11:39:10 AM		TEXAS INSTRUMENTS



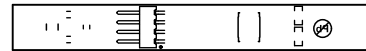
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 2	TID #: TIDA-01335		
PLOT NAME = Signal Layer 2	GENERATED : 7/18/2017 11:39:11 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01335		
PLOT NAME = Bottom Layer	GENERATED : 7/18/2017 11:39:13 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01335		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/18/2017 11:39:14 AM	TEXAS INSTRUMENTS	

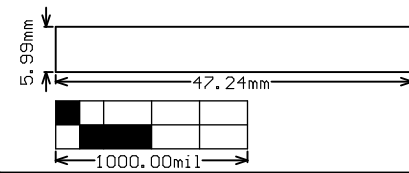


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01335		
PLOT NAME = Bottom Overlay	GENERATED : 7/18/2017 11:39:15 AM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	14	8.00mil (0.203mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	13	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	40	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
☆	10	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
■	1	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
	78 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01335		
PLOT NAME = Drill Drawing	GENERATED : 7/18/2017	11:39:17 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01335	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01335		
PLOT NAME = Board Dimensions	GENERATED : 7/18/2017 11:39:18 AM	TEXAS INSTRUMENTS	

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